

ABSTRACT OF THE DISCLOSURE

The invention provides a thermoplastic resin composition having excellent blister resistance, which
5 does not cause blister on the surfaces of resinous parts by passing through a reflowing oven when the resin composition is used as a resin material forming the resinous parts subjected to the surface-mount technology system, particularly, a thermoplastic resin composition
10 high in mechanical strength such as flexural strength, weld strength and tensile elongation and excellent in moldability and friction property. The resin composition contains a polyamide resin component composed of 5 to 95% by weight of the following component (A) and 5 to 95% by
15 weight of the following component (B):
Component (A): a polyamide resin obtained by polycondensing diamine(s) including at least tetramethylenediamine with dicarboxylic acid(s) including at least adipic acid; and
20 Component (B): a polyamide resin obtained by polycondensing diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine with dicarboxylic acid(s) including at least terephthalic acid.